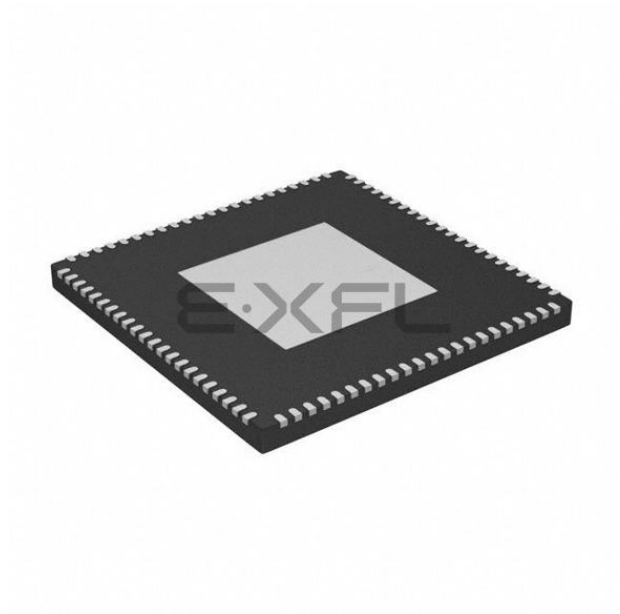

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Active
Type	Blackfin+
Interface	CAN, DSPI, EBI/EMI, I²C, PPI, QSPI, SD/SDIO, SPI, SPORT, UART/USART, USB OTG
Clock Rate	300MHz
Non-Volatile Memory	ROM (512kB)
On-Chip RAM	512kB
Voltage - I/O	1.8V, 3.3V
Voltage - Core	1.10V
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	88-VFQFN Exposed Pad, CSP
Supplier Device Package	88-LFCSP-VQ (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/adsp-bf704bcpz-3

output enable and the input enable of a GPIO pin are both active, the data signal before the pad driver is looped back to the receive path for the same GPIO pin.

MEMORY ARCHITECTURE

The processor views memory as a single unified 4G byte address space, using 32-bit addresses. All resources, including internal memory, external memory, and I/O control registers, occupy separate sections of this common address space. The memory portions of this address space are arranged in a hierarchical structure to provide a good cost/performance balance of some very fast, low-latency core-accessible memory as cache or SRAM, and larger, lower-cost and performance interface-accessible memory systems. See Figure 3.

Internal (Core-Accessible) Memory

The L1 memory system is the highest-performance memory available to the Blackfin+ processor core.

The core has its own private L1 memory. The modified Harvard architecture supports two concurrent 32-bit data accesses along with an instruction fetch at full processor speed which provides high-bandwidth processor performance. In the core, a 64K byte block of data memory partners with an 64K byte memory block for instruction storage. Each data block is multibanked for efficient data exchange through DMA and can be configured as SRAM. Alternatively, 16K bytes of each block can be configured in L1 cache mode. The four-way set-associative instruction cache and the 2 two-way set-associative data caches greatly accelerate memory access performance, especially when accessing external memories.

The L1 memory domain also features a 8K byte data SRAM block which is ideal for storing local variables and the software stack. All L1 memory is protected by a multi-parity-bit concept, regardless of whether the memory is operating in SRAM or cache mode.

Outside of the L1 domain, L2 and L3 memories are arranged using a Von Neumann topology. The L2 memory domain is a unified instruction and data memory and can hold any mixture of code and data required by the system design. The L2 memory domain is accessible by the Blackfin+ core through a dedicated 64-bit interface. It operates at SYSCLK frequency.

The processor features up to 1M byte of L2 SRAM, which is ECC-protected and organized in eight banks. Individual banks can be made private to any system master. There is also a 512K byte single-bank ROM in the L2 domain. It contains boot code, security code, and general-purpose ROM space.

OTP Memory

The processor features 4 kB of one-time-programmable (OTP) memory which is memory-map accessible. This memory stores a unique chip identification and is used to support secure-boot and secure operation.

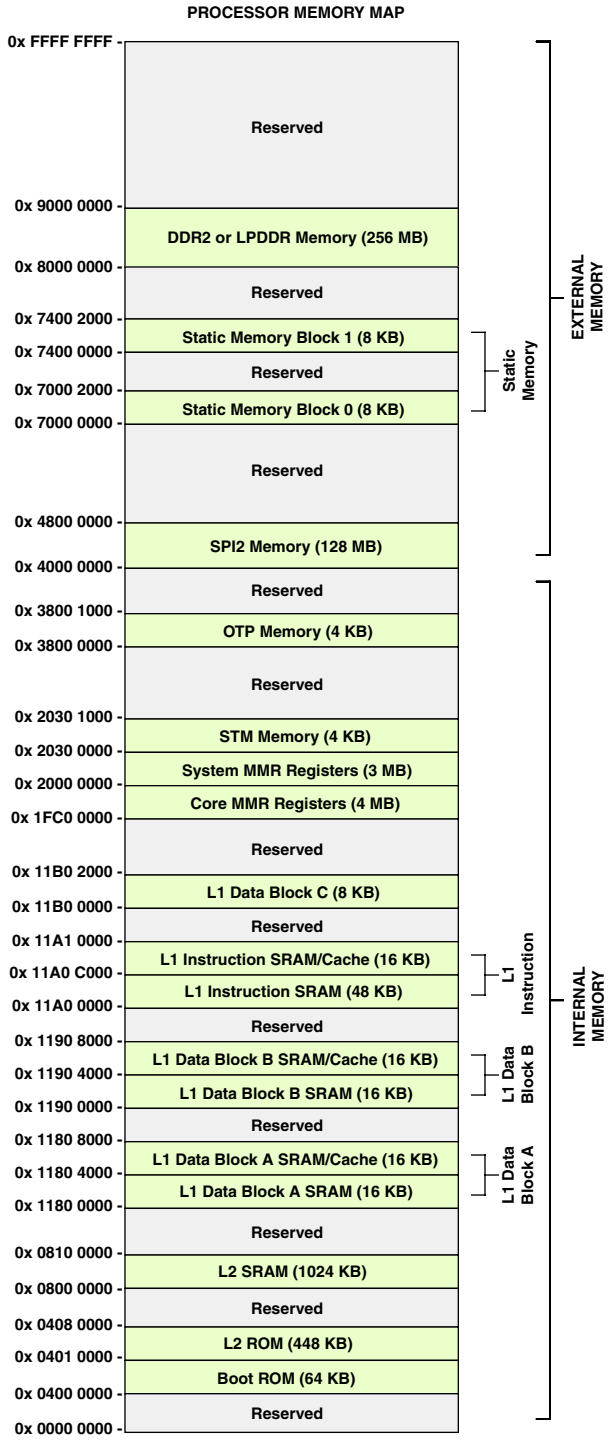


Figure 3. ADSP-BF706/ADSP-BF707 Internal/External Memory Map

SECURITY FEATURES DISCLAIMER

To our knowledge, the Security Features, when used in accordance with the data sheet and hardware reference manual specifications, provide a secure method of implementing code and data safeguards. However, Analog Devices does not guarantee that this technology provides absolute security. ACCORDINGLY, ANALOG DEVICES HEREBY DISCLAIMS ANY AND ALL EXPRESS AND IMPLIED WARRANTIES THAT THE SECURITY FEATURES CANNOT BE BREACHED, COMPROMISED, OR OTHERWISE CIRCUMVENTED AND IN NO EVENT SHALL ANALOG DEVICES BE LIABLE FOR ANY LOSS, DAMAGE, DESTRUCTION, OR RELEASE OF DATA, INFORMATION, PHYSICAL PROPERTY, OR INTELLECTUAL PROPERTY.

Table 6. ADSP-BF70x Detailed Signal Descriptions (Continued)

Port Name	Direction	Description
SPT_BCLK	I/O	**Channel B Clock.** Data and Frame Sync are driven/sampled with respect to this clock. This signal can be either internally or externally generated.
SPT_BD0	I/O	**Channel B Data 0.** Primary bidirectional data I/O. This signal can be configured as an output to transmit serial data, or as an input to receive serial data.
SPT_BD1	I/O	**Channel B Data 1.** Secondary bidirectional data I/O. This signal can be configured as an output to transmit serial data, or as an input to receive serial data.
SPT_BFS	I/O	**Channel B Frame Sync.** The frame sync pulse initiates shifting of serial data. This signal is either generated internally or externally.
SPT_BTDV	Output	**Channel B Transmit Data Valid.** This signal is optional and only active when SPORT is configured in multi-channel transmit mode. It is asserted during enabled slots.
SYS_BMODEn	Input	**Boot Mode Control n.** Selects the boot mode of the processor.
SYS_CLKIN	Input	**Clock/Crystal Input.** Connect to an external clock source or crystal.
SYS_CLKOUT	Output	**Processor Clock Output.** Outputs internal clocks. Clocks may be divided down. See the CGU chapter of the HRM for more details.
SYS_EXTWAKE	Output	**External Wake Control.** Drives low during hibernate and high all other times. Typically connected to the enable input of the voltage regulator controlling the VDD_INT supply.
$\overline{\text{SYS\_FAULT}}$	I/O	**Active-Low Fault Output.** Indicates internal faults or senses external faults depending on the operating mode.
$\overline{\text{SYS\_HWRST}}$	Input	**Processor Hardware Reset Control.** Resets the device when asserted.
$\overline{\text{SYS\_NMI}}$	Input	**Non-maskable Interrupt.** See the processor hardware and programming references for more details.
$\overline{\text{SYS\_RESOUT}}$	Output	**Reset Output.** Indicates that the device is in the reset or hibernate state.
SYS_WAKEn	Input	**Power Saving Mode Wakeup n.** Wake-up source input for deep sleep and/or hibernate mode.
SYS_XTAL	Output	**Crystal Output.** Drives an external crystal. Must be left unconnected if an external clock is driving CLKIN.
JTG_SWCLK	I/O	**Serial Wire Clock.** Clocks data into and out of the target during debug.
JTG_SWDIO	I/O	**Serial Wire DIO.** Sends and receives serial data to and from the target during debug.
JTG_SWO	Output	**Serial Wire Out.** Provides trace data to the emulator.
JTG_TCK	Input	**JTAG Clock.** JTAG test access port clock.
JTG_TDI	Input	**JTAG Serial Data In.** JTAG test access port data input.
JTG_TDO	Output	**JTAG Serial Data Out.** JTAG test access port data output.
JTG_TMS	Input	**JTAG Mode Select.** JTAG test access port mode select.
$\overline{\text{JTG\_TRST}}$	Input	**JTAG Reset.** JTAG test access port reset.
TM_ACIn	Input	**Alternate Capture Input n.** Provides an additional input for WIDCAP, WATCHDOG, and PININT modes.
TM_ACLKn	Input	**Alternate Clock n.** Provides an additional time base for use by an individual timer.
TM_CLK	Input	**Clock.** Provides an additional global time base for use by all the GP timers.
TM_TMRn	I/O	**Timer n.** The main input/output signal for each timer.
TRACE_CLK	Output	**Trace Clock.** Clock output.
TRACE_Dnn	Output	**Trace Data n.** Unidirectional data bus.
TWI_SCL	I/O	**Serial Clock.** Clock output when master, clock input when slave.
TWI_SDA	I/O	**Serial Data.** Receives or transmits data.
$\overline{\text{UART\_CTS}}$	Input	**Clear to Send.** Flow control signal.
$\overline{\text{UART\_RTS}}$	Output	**Request to Send.** Flow control signal.
$\overline{\text{UART\_RX}}$	Input	**Receive.** Receive input. Typically connects to a transceiver that meets the electrical requirements of the device being communicated with.
$\overline{\text{UART\_TX}}$	Output	**Transmit.** Transmit output. Typically connects to a transceiver that meets the electrical requirements of the device being communicated with.
USB_CLKIN	Input	**Clock/Crystal Input.** This clock input is multiplied by a PLL to form the USB clock. See data sheet specifications for frequency/tolerance information.

Table 7. ADSP-BF70x 184-Ball CSP_BGA Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
SPI2_D2	SPI2 Data 2	B	PB_13
SPI2_D3	SPI2 Data 3	B	PB_14
SPI2_MISO	SPI2 Master In, Slave Out	B	PB_11
SPI2_MOSI	SPI2 Master Out, Slave In	B	PB_12
SPI2_RDY	SPI2 Ready	A	PA_04
$\overline{\text{SPI2\_SEL1}}$	SPI2 Slave Select Output 1	B	PB_15
$\overline{\text{SPI2\_SEL2}}$	SPI2 Slave Select Output 2	B	PB_08
$\overline{\text{SPI2\_SEL3}}$	SPI2 Slave Select Output 3	B	PB_09
$\overline{\text{SPI2\_SS}}$	SPI2 Slave Select Input	B	PB_15
SPT0_ACLK	SPORT0 Channel A Clock	A	PA_13
SPT0_ACLK	SPORT0 Channel A Clock	C	PC_09
SPT0_AD0	SPORT0 Channel A Data 0	A	PA_14
SPT0_AD0	SPORT0 Channel A Data 0	C	PC_08
SPT0_AD1	SPORT0 Channel A Data 1	C	PC_00
SPT0_AFS	SPORT0 Channel A Frame Sync	A	PA_12
SPT0_AFS	SPORT0 Channel A Frame Sync	C	PC_05
SPT0_ATDV	SPORT0 Channel A Transmit Data Valid	A	PA_15
SPT0_BCLK	SPORT0 Channel B Clock	B	PB_04
SPT0_BCLK	SPORT0 Channel B Clock	C	PC_04
SPT0_BD0	SPORT0 Channel B Data 0	B	PB_05
SPT0_BD0	SPORT0 Channel B Data 0	C	PC_06
SPT0_BD1	SPORT0 Channel B Data 1	B	PB_07
SPT0_BD1	SPORT0 Channel B Data 1	C	PC_01
SPT0_BFS	SPORT0 Channel B Frame Sync	B	PB_06
SPT0_BFS	SPORT0 Channel B Frame Sync	C	PC_07
SPT0_BTDV	SPORT0 Channel B Transmit Data Valid	A	PA_15
SPT1_ACLK	SPORT1 Channel A Clock	A	PA_08
SPT1_AD0	SPORT1 Channel A Data 0	A	PA_10
SPT1_AD1	SPORT1 Channel A Data 1	A	PA_11
SPT1_AFS	SPORT1 Channel A Frame Sync	A	PA_09
SPT1_ATDV	SPORT1 Channel A Transmit Data Valid	A	PA_07
SPT1_BCLK	SPORT1 Channel B Clock	B	PB_00
SPT1_BCLK	SPORT1 Channel B Clock	C	PC_10
SPT1_BD0	SPORT1 Channel B Data 0	B	PB_02
SPT1_BD0	SPORT1 Channel B Data 0	C	PC_12
SPT1_BD1	SPORT1 Channel B Data 1	B	PB_03
SPT1_BD1	SPORT1 Channel B Data 1	C	PC_13
SPT1_BFS	SPORT1 Channel B Frame Sync	B	PB_01
SPT1_BFS	SPORT1 Channel B Frame Sync	C	PC_11
SPT1_BTDV	SPORT1 Channel B Transmit Data Valid	A	PA_07
SPT1_BTDV	SPORT1 Channel B Transmit Data Valid	C	PC_14
SYS_BMODE0	Boot Mode Control 0	Not Muxed	SYS_BMODE0
SYS_BMODE1	Boot Mode Control 1	Not Muxed	SYS_BMODE1
SYS_CLKIN	Clock/Crystal Input	Not Muxed	SYS_CLKIN
SYS_CLKOUT	Processor Clock Output	Not Muxed	SYS_CLKOUT
SYS_EXTWAKE	External Wake Control	Not Muxed	SYS_EXTWAKE

Table 10. Signal Multiplexing for Port C

Signal Name	Multiplexed Function 0	Multiplexed Function 1	Multiplexed Function 2	Multiplexed Function 3	Multiplexed Function Input Tap
PC_00	UART1_TX	SPT0_AD1	PPI0_D15		
PC_01	UART1_RX	SPT0_BD1	PPI0_D14	SMC0_A09	TM0_ACI4
PC_02	UART0_RTS	CAN0_RX	PPI0_D13	SMC0_A10	TM0_ACI5/SYS_ WAKE3
PC_03	UART0_CTS	CAN0_TX	PPI0_D12	SMC0_A11	TM0_ACI0
PC_04	SPT0_BCLK	SPI0_CLK	MSI0_D1	SMC0_A12	TM0_ACLK0
PC_05	SPT0_AFS	TM0_TMR3	MSI0_CMD		
PC_06	SPT0_BD0	SPI0_MISO	MSI0_D3		
PC_07	SPT0_BFS	SPI0_MOSI	MSI0_D2		TM0_ACI2
PC_08	SPT0_AD0	SPI0_D2	MSI0_D0		
PC_09	SPT0_ACLK	SPI0_D3	MSI0_CLK		TM0_ACLK2
PC_10	SPT1_BCLK	MSI0_D4	SPI1_SEL3		TM0_ACLK1
PC_11	SPT1_BFS	MSI0_D5	SPI0_SEL3		
PC_12	SPT1_BD0	MSI0_D6			
PC_13	SPT1_BD1	MSI0_D7			
PC_14	SPT1_BTDV	MSI0_INT			

Table 11. ADSP-BF70x 12 mm × 12 mm 88-Lead LFCSP (QFN) Signal Descriptions (Continued)

Signal Name	Description	Port	Pin Name
PPI0_D08	EPPI0 Data 8	A	PA_11
PPI0_D09	EPPI0 Data 9	A	PA_10
PPI0_D10	EPPI0 Data 10	A	PA_09
PPI0_D11	EPPI0 Data 11	A	PA_08
PPI0_D12	EPPI0 Data 12	C	PC_03
PPI0_D13	EPPI0 Data 13	C	PC_02
PPI0_D14	EPPI0 Data 14	C	PC_01
PPI0_D15	EPPI0 Data 15	C	PC_00
PPI0_D16	EPPI0 Data 16	B	PB_08
PPI0_D17	EPPI0 Data 17	B	PB_09
PPI0_FS1	EPPI0 Frame Sync 1 (HSYNC)	A	PA_12
PPI0_FS2	EPPI0 Frame Sync 2 (VSYNC)	A	PA_13
PPI0_FS3	EPPI0 Frame Sync 3 (FIELD)	A	PA_15
RTC0_CLKIN	RTC0 Crystal input/external oscillator connection	Not Muxed	RTC0_CLKIN
RTC0_XTAL	RTC0 Crystal output	Not Muxed	RTC0_XTAL
SMC0_A01	SMC0 Address 1	A	PA_08
SMC0_A02	SMC0 Address 2	A	PA_09
SMC0_A03	SMC0 Address 3	A	PA_10
SMC0_A04	SMC0 Address 4	A	PA_11
SMC0_A05	SMC0 Address 5	A	PA_07
SMC0_A06	SMC0 Address 6	A	PA_06
SMC0_A07	SMC0 Address 7	A	PA_05
SMC0_A08	SMC0 Address 8	A	PA_04
SMC0_A09	SMC0 Address 9	C	PC_01
SMC0_A10	SMC0 Address 10	C	PC_02
SMC0_A11	SMC0 Address 11	C	PC_03
SMC0_A12	SMC0 Address 12	C	PC_04
$\overline{\text{SMC0\_ABE0}}$	SMC0 Byte Enable 0	A	PA_00
$\overline{\text{SMC0\_ABE1}}$	SMC0 Byte Enable 1	A	PA_01
$\overline{\text{SMC0\_AMS0}}$	SMC0 Memory Select 0	A	PA_15
$\overline{\text{SMC0\_AMS1}}$	SMC0 Memory Select 1	A	PA_02
$\overline{\text{SMC0\_AOE}}$	SMC0 Output Enable	A	PA_12
SMC0_ARDY	SMC0 Asynchronous Ready	A	PA_03
$\overline{\text{SMC0\_ARE}}$	SMC0 Read Enable	A	PA_13
$\overline{\text{SMC0\_AWE}}$	SMC0 Write Enable	A	PA_14
SMC0_D00	SMC0 Data 0	B	PB_07
SMC0_D01	SMC0 Data 1	B	PB_06
SMC0_D02	SMC0 Data 2	B	PB_05
SMC0_D03	SMC0 Data 3	B	PB_04
SMC0_D04	SMC0 Data 4	B	PB_03
SMC0_D05	SMC0 Data 5	B	PB_02
SMC0_D06	SMC0 Data 6	B	PB_01
SMC0_D07	SMC0 Data 7	B	PB_00
SMC0_D08	SMC0 Data 8	B	PB_08
SMC0_D09	SMC0 Data 9	B	PB_09
SMC0_D10	SMC0 Data 10	B	PB_10

Table 15. ADSP-BF70x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Hiber Term	Hiber Drive	Power Domain	Description and Notes
GND_HADC	g	na	none	none	none	none	none	na	Desc: Ground HADC Notes: If HADC is not used, connect to ground.
HADC0_VIN0	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 0 Notes: If HADC is not used, connect to ground.
HADC0_VIN1	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 1 Notes: If HADC is not used, connect to ground.
HADC0_VIN2	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 2 Notes: If HADC is not used, connect to ground.
HADC0_VIN3	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 Analog Input at channel 3 Notes: If HADC is not used, connect to ground.
HADC0_VREFN	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 Ground Reference for ADC Notes: If HADC is not used, connect to ground.
HADC0_VREFP	a	na	none	none	none	none	none	VDD_HADC	Desc: HADC0 External Reference for ADC Notes: If HADC is not used, connect to ground.
JTG_TCK_ SWCLK	I/O	na	pd	none	none	none	none	VDD_EXT	Desc: JTAG Clock | Serial Wire Clock Notes: Functional during reset.
JTG_TDI	I/O	na	pu	none	none	none	none	VDD_EXT	Desc: JTAG Serial Data In Notes: Functional during reset.
JTG_TDO_SWO	I/O	A	none	none	none	none	none	VDD_EXT	Desc: JTAG Serial Data Out | Serial Wire Out Notes: Functional during reset, three-state when $\overline{\text{JTG\_TRST}}$ is asserted.
JTG_TMS_ SWDIO	I/O	A	pu	none	none	none	none	VDD_EXT	Desc: JTAG Mode Select | Serial Wire DIO Notes: Functional during reset.
$\overline{\text{JTG\_TRST}}$	I/O	na	pd	none	none	none	none	VDD_EXT	Desc: JTAG Reset Notes: Functional during reset, a 10k external pull-down may be used to shorten the t_{VDDEXT_RST} timing requirement.
PA_00	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI1 Clock | TRACE0 Trace Data 7 | SMC0 Byte Enable 0 Notes: SPI clock requires a pull-down when controlling most SPI flash devices.
PA_01	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI1 Master In, Slave Out | TRACE0 Trace Data 6 | SMC0 Byte Enable 1 Notes: Pull-up required for SPI_MISO if SPI master boot is used.

Table 15. ADSP-BF70x Designer Quick Reference (Continued)

Signal Name	Type	Driver Type	Int Term	Reset Term	Reset Drive	Hiber Term	Hiber Drive	Power Domain	Description and Notes
PB_12	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI2 Master Out, Slave In | TRACE0 Trace Data 3 | SMC0 Data 12 | SYS Power Saving Mode Wakeup 2 Notes: If hibernate mode is used, one of the following must be true during hibernate. Either this pin must be actively driven by another IC, or it must have a pull-up or pull-down.
PB_13	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI2 Data 2 | UART1 Request to Send | TRACE0 Trace Data 2 | SMC0 Data 13 Notes: No notes.
PB_14	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI2 Data 3 | UART1 Clear to Send | TRACE0 Trace Data 1 | SMC0 Data 14 Notes: No notes.
PB_15	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPI2 Slave Select Output 1 | TRACE0 Trace Data 0 | SMC0 Data 15 | SPI2 Slave Select Input Notes: SPI slave select outputs require a pull-up when used.
PC_00	I/O	A	none	none	none	none	none	VDD_EXT	Desc: UART1 Transmit | SPT0 Channel A Data 1 | PPI0 Data 15 Notes: No notes.
PC_01	I/O	A	none	none	none	none	none	VDD_EXT	Desc: UART1 Receive | SPT0 Channel B Data 1 | PPI0 Data 14 | SMC0 Address 9 | TM0 Alternate Capture Input 4 Notes: No notes.
PC_02	I/O	A	none	none	none	none	none	VDD_EXT	Desc: UART0 Request to Send | CAN0 Receive | PPI0 Data 13 | SMC0 Address 10 | SYS Power Saving Mode Wakeup 3 | TM0 Alternate Capture Input 5 Notes: If hibernate mode is used, one of the following must be true during hibernate. Either this pin must be actively driven by another IC, or it must have a pull-up or pull-down.
PC_03	I/O	A	none	none	none	none	none	VDD_EXT	Desc: UART0 Clear to Send | CAN0 Transmit | PPI0 Data 12 | SMC0 Address 11 | TM0 Alternate Capture Input 0 Notes: No notes.
PC_04	I/O	A	none	none	none	none	none	VDD_EXT	Desc: SPT0 Channel B Clock | SPI0 Clock | MSI0 Data 1 | SMC0 Address 12 | TM0 Alternate Clock 0 Notes: An external pull-up may be required for MSI modes, see the MSI chapter in the hardware reference for details.

Table 18. Peripheral Clock Operating Conditions

Parameter		Restriction	Min	Typ	Max	Unit
f_{OCLK}	Output Clock Frequency				50	MHz
$f_{SYS\_CLKOUTJ}$	SYS_CLKOUT Period Jitter[1, 2]			±2		%
$f_{PCLKPROG}$	Programmed PPI Clock When Transmitting Data and Frame Sync				50	MHz
$f_{PCLKPROG}$	Programmed PPI Clock When Receiving Data or Frame Sync				50	MHz
$f_{PCLKEXT}$	External PPI Clock When Receiving Data and Frame Sync[3, 4]	$f_{PCLKEXT} \le f_{SCLK0}$			50	MHz
$f_{PCLKEXT}$	External PPI Clock Transmitting Data or Frame Sync[3, 4]	$f_{PCLKEXT} \le f_{SCLK0}$			50	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Transmitting Data and Frame Sync				50	MHz
$f_{SPTCLKPROG}$	Programmed SPT Clock When Receiving Data or Frame Sync				50	MHz
$f_{SPTCLKEXT}$	External SPT Clock When Receiving Data and Frame Sync[3, 4]	$f_{SPTCLKEXT} \le f_{SCLK0}$			50	MHz
$f_{SPTCLKEXT}$	External SPT Clock Transmitting Data or Frame Sync[3, 4]	$f_{SPTCLKEXT} \le f_{SCLK0}$			50	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Transmitting Data				50	MHz
$f_{SPICLKPROG}$	Programmed SPI Clock When Receiving Data				50	MHz
$f_{SPICLKEXT}$	External SPI Clock When Receiving Data[3, 4]	$f_{SPICLKEXT} \le f_{SCLK0}$			50	MHz
$f_{SPICLKEXT}$	External SPI Clock When Transmitting Data[3, 4]	$f_{SPICLKEXT} \le f_{SCLK0}$			50	MHz
$f_{MSICLKPROG}$	Programmed MSI Clock				50	MHz

[1] SYS_CLKOUT jitter is dependent on the application system design including pin switching activity, board layout, and the jitter characteristics of the SYS_CLKIN source. Due to the dependency on these factors the measured jitter may be higher or lower than this typical specification for each end application.
[2] The value in the Typ field is the percentage of the SYS_CLKOUT period.
[3] The maximum achievable frequency for any peripheral in external clock mode is dependent on being able to meet the setup and hold times in the ac timing specifications section for that peripheral. Pay particular attention to setup and hold times for VDD_EXT = 1.8 V which may preclude the maximum frequency listed here.
[4] The peripheral external clock frequency must also be less than or equal to the f_{SCLK} that clocks the peripheral.

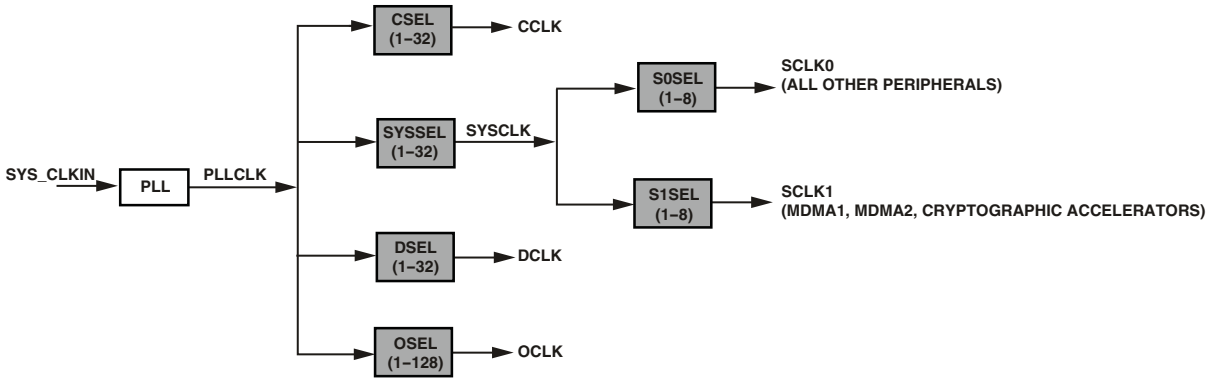


Figure 6. Clock Relationships and Divider Values

Table 19. Phase-Locked Loop Operating Conditions

Parameter		Min	Max	Unit
f_{PLLCLK}	PLL Clock Frequency	230.2	800	MHz
CGU_CTL.MSEL[1]	PLL Multiplier	8	41	

[1] The CGU_CTL.MSEL setting must also be chosen to ensure that the f_{PLLCLK} specification is not violated.

ELECTRICAL CHARACTERISTICS

Parameter		Test Conditions/Comments	Min	Typ	Max	Unit
V_{OH}[1]	High Level Output Voltage	V_{DD_EXT} = 1.7 V, I_{OH} = –1.0 mA	0.8 × V_{DD_EXT}			V
V_{OH}[1]	High Level Output Voltage	V_{DD_EXT} = 3.13 V, I_{OH} = –2.0 mA	0.9 × V_{DD_EXT}			V
V_{OH_DDR2}[2]	High Level Output Voltage, DDR2, Programmed Impedance = 34 Ω	V_{DD_DMC} = 1.70 V, I_{OH} = –7.1 mA	V_{DD_DMC} – 0.320			V
V_{OH_DDR2}[2]	High Level Output Voltage, DDR2, Programmed Impedance = 40 Ω	V_{DD_DMC} = 1.70 V, I_{OH} = –5.8 mA	V_{DD_DMC} – 0.320			V
V_{OH_DDR2}[2]	High Level Output Voltage, DDR2, Programmed Impedance = 50 Ω	V_{DD_DMC} = 1.70 V, I_{OH} = –4.1 mA	V_{DD_DMC} – 0.320			V
V_{OH_DDR2}[2]	High Level Output Voltage, DDR2, Programmed Impedance = 60 Ω	V_{DD_DMC} = 1.70 V, I_{OH} = –3.4 mA	V_{DD_DMC} – 0.320			V
V_{OH_LPDDR}[2]	High Level Output Voltage, LPDDR	V_{DD_DMC} = 1.70 V, I_{OH} = –2.0 mA	V_{DD_DMC} – 0.320			V
V_{OL}[3]	Low Level Output Voltage	V_{DD_EXT} = 1.7 V, I_{OL} = 1.0 mA			0.400	V
V_{OL}[3]	Low Level Output Voltage	V_{DD_EXT} = 3.13 V, I_{OL} = 2.0 mA			0.400	V
V_{OL_DDR2}[2]	Low Level Output Voltage, DDR2, Programmed Impedance = 34 Ω	V_{DD_DMC} = 1.70 V, I_{OL} = 7.1 mA			0.320	V
V_{OL_DDR2}[2]	Low Level Output Voltage, DDR2, Programmed Impedance = 40 Ω	V_{DD_DMC} = 1.70 V, I_{OL} = 5.8 mA			0.320	V
V_{OL_DDR2}[2]	Low Level Output Voltage, DDR2, Programmed Impedance = 50 Ω	V_{DD_DMC} = 1.70 V, I_{OL} = 4.1 mA			0.320	V
V_{OL_DDR2}[2]	Low Level Output Voltage, DDR2, Programmed Impedance = 60 Ω	V_{DD_DMC} = 1.70 V, I_{OL} = 3.4 mA			0.320	V
V_{OL_LPDDR}[2]	Low Level Output Voltage, LPDDR	V_{DD_DMC} = 1.70 V, I_{OL} = 2.0 mA			0.320	V
I_{IH}[4]	High Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			10	µA
$I_{IH\_DMC0\_VREF}$[5]	High Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			1	µA
I_{IH_PD}[6]	High Level Input Current with Pull-down Resistor	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			100	µA
R_{PD}[6]	Internal Pull-down Resistance	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V	57		130	kΩ
I_{IL}[7]	Low Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V			10	µA
$I_{IL\_DMC0\_VREF}$[5]	Low Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V			1	µA
I_{IL_PU}[8]	Low Level Input Current with Pull-up Resistor	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V			100	µA
R_{PU}[8]	Internal Pull-up Resistance	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V	53		129	kΩ
I_{IH_USB0}[9]	High Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			10	µA
I_{IL_USB0}[9]	Low Level Input Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V			10	µA
I_{OZH}[10]	Three-State Leakage Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			10	µA
I_{OZH}[11]	Three-State Leakage Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 1.9 V			10	µA
I_{OZL}[12]	Three-State Leakage Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 0 V			10	µA
I_{OZH_PD}[13]	Three-State Leakage Current	V_{DD_EXT} = 3.47 V, V_{DD_DMC} = 1.9 V, V_{DD_USB} = 3.47 V, V_{IN} = 3.47 V			100	µA

Asynchronous Flash Read

Table 33 and Figure 12 show asynchronous flash memory read timing, related to the static memory controller (SMC).

Table 33. Asynchronous Flash Read

Parameter		V_{DD_EXT} 1.8 V/3.3 V Nominal Min	Max	Unit
Switching Characteristics				
t_{AMSADV}	SMC0_Ax (Address)/$\overline{\text{SMC0\_AMSx}}$ Assertion Before SMC0_NORDV Low[1]	PREST × t_{SCLK0} – 2		ns
t_{WADV}	SMC0_NORDV Active Low Width[2]	RST × t_{SCLK0} – 2		ns
$t_{DADVARE}$	$\overline{\text{SMC0\_ARE}}$ Low Delay From SMC0_NORDV High[3]	PREAT × t_{SCLK0} – 2		ns
t_{HARE}	Output[4] Hold After $\overline{\text{SMC0\_ARE}}$ High[5]	RHT × t_{SCLK0} – 2		ns
t_{WARE}[6]	$\overline{\text{SMC0\_ARE}}$ Active Low Width[7]	RAT × t_{SCLK0} – 2		ns

[1] PREST value set using the SMC_BxETIM.PREST bits.
[2] RST value set using the SMC_BxTIM.RST bits.
[3] PREAT value set using the SMC_BxETIM.PREAT bits.
[4] Output signals are SMC0_Ax, $\overline{\text{SMC0\_AMS}}$, $\overline{\text{SMC0\_AOE}}$.
[5] RHT value set using the SMC_BxTIM.RHT bits.
[6] SMC0_BxCTL.ARDYEN bit = 0.
[7] RAT value set using the SMC_BxTIM.RAT bits.

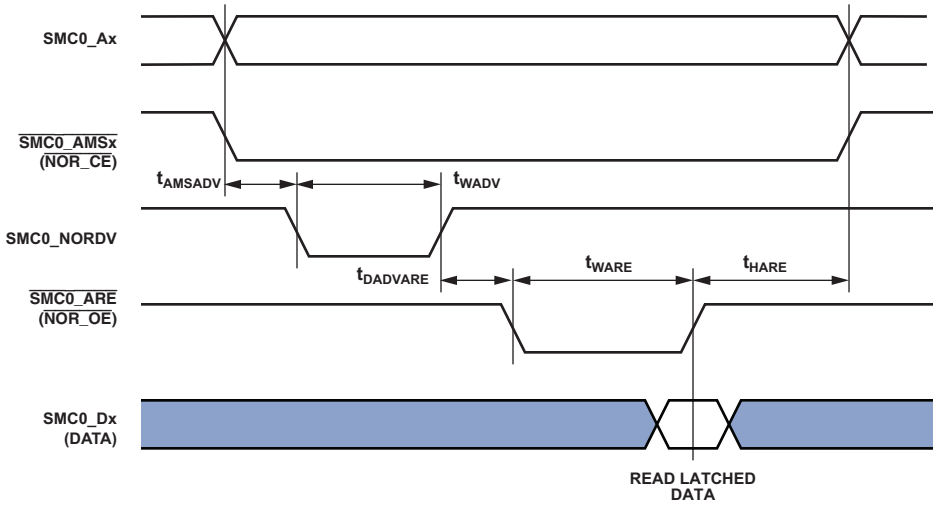


Figure 12. Asynchronous Flash Read

Asynchronous Flash Write

Table 37 and Figure 16 show asynchronous flash memory write timing, related to the static memory controller (SMC).

Table 37. Asynchronous Flash Write

Parameter		V_{DD_EXT} 1.8 V/3.3 V Nominal Min	Max	Unit
Switching Characteristics				
t_{AMSADV}	SMC0_Ax/$\overline{\text{SMC0\_AMSx}}$ Assertion Before ADV Low[1]	PREST × t_{SCLK0} – 2		ns
$t_{DADVAWE}$	$\overline{\text{SMC0\_AWE}}$ Low Delay From ADV High[2]	PREAT × t_{SCLK0} – 4		ns
t_{WADV}	NR_ADV Active Low Width[3]	WST × t_{SCLK0} – 2		ns
t_{HAWE}	Output[4] Hold After $\overline{\text{SMC0\_AWE}}$ High[5]	WHT × t_{SCLK0}		ns
t_{WAWE}[6]	$\overline{\text{SMC0\_AWE}}$ Active Low Width[7]	WAT × t_{SCLK0} – 2		ns

[1] PREST value set using the SMC_BxETIM.PREST bits.
[2] PREAT value set using the SMC_BxETIM.PREAT bits.
[3] WST value set using the SMC_BxTIM.WST bits.
[4] Output signals are DATA, SMC0_Ax, $\overline{\text{SMC0\_AMSx}}$, $\overline{\text{SMC0\_ABEx}}$.
[5] WHT value set using the SMC_BxTIM.WHT bits.
[6] SMC_BxCTL.ARDYEN bit = 0.
[7] WAT value set using the SMC_BxTIM.WAT bits.

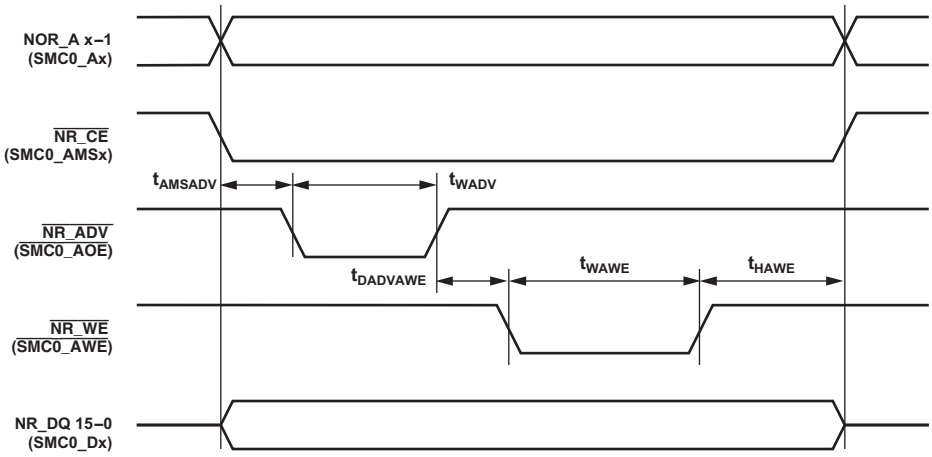


Figure 16. Asynchronous Flash Write

All Accesses

Table 38 describes timing that applies to all memory accesses, related to the static memory controller (SMC).

Table 38. All Accesses

Parameter		V_{DD_EXT} 1.8 V Nominal Min	Max	V_{DD_EXT} 3.3 V Nominal Min	Max	Unit
Switching Characteristic						
t_{TURN}	$\overline{\text{SMC0\_AMSx}}$ Inactive Width	(IT + TT) × t_{SCLK0} – 2		(IT + TT) × t_{SCLK0} – 2		ns

Up/Down Counter/Rotary Encoder Timing

Table 47 and Figure 25 describe timing, related to the general-purpose counter (CNT).

Table 47. Up/Down Counter/Rotary Encoder Timing

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Timing Requirement						
t_{WCOUNT}	Up/Down Counter/Rotary Encoder Input Pulse Width	$2 \times t_{SCLK0}$		$2 \times t_{SCLK0}$		ns

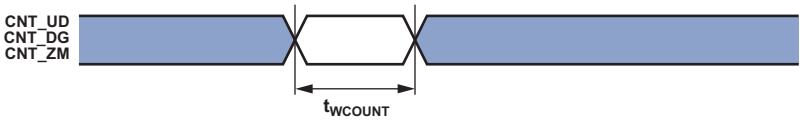


Figure 25. Up/Down Counter/Rotary Encoder Timing

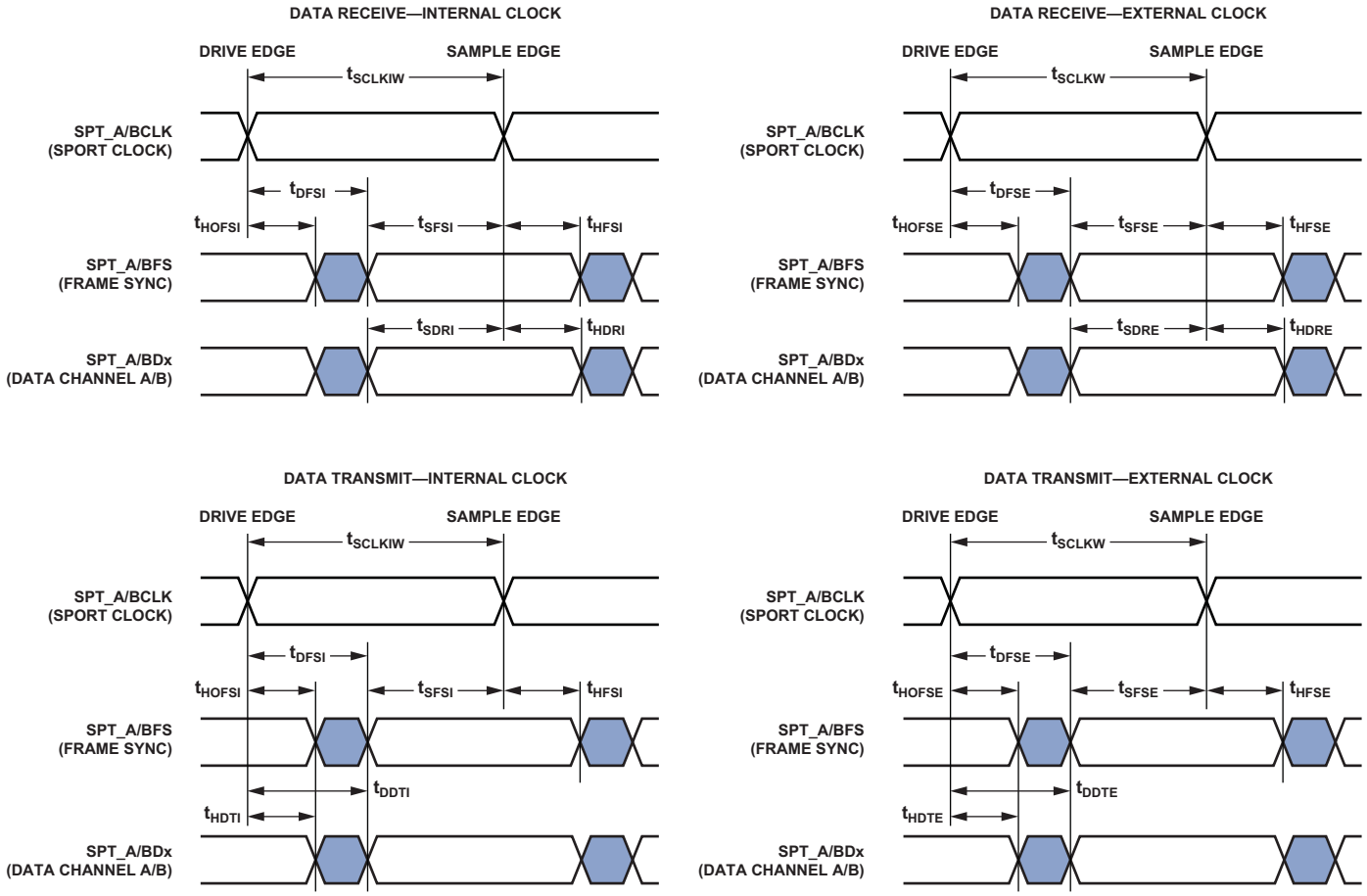


Figure 27. Serial Ports

Enhanced Parallel Peripheral Interface Timing

The following tables and figures describe enhanced parallel peripheral interface timing operations. The POLC bits in the EPPI_CTL register may be used to set the sampling/driving edges of the EPPI clock.

When internally generated, the programmed PPI clock ($f_{PCLKPROG}$) frequency in MHz is set by the following equation where VALUE is a field in the EPPI_CLKDIV register that can be set from 0 to 65,535:

$$f_{PCLKPROG} = \frac{f_{SCLK0}}{(VALUE + 1)}$$

$$t_{PCLKPROG} = \frac{1}{f_{PCLKPROG}}$$

When externally generated the EPPI_CLK is called $f_{PCLKEXT}$:

$$t_{PCLKEXT} = \frac{1}{f_{PCLKEXT}}$$

Table 60. Enhanced Parallel Peripheral Interface—Internal Clock

Parameter		V_{DD_EXT} 1.8 V Nominal Min	V_{DD_EXT} 1.8 V Nominal Max	V_{DD_EXT} 3.3 V Nominal Min	V_{DD_EXT} 3.3 V Nominal Max	Unit
Timing Requirements						
t_{SFSPI}	External FS Setup Before EPPI_CLK	6.5		5		ns
t_{HFSPI}	External FS Hold After EPPI_CLK	1.5		1		ns
t_{SDRPI}	Receive Data Setup Before EPPI_CLK	6.4		5		ns
t_{HDRPI}	Receive Data Hold After EPPI_CLK	1		1		ns
t_{SFS3GI}	External FS3 Input Setup Before EPPI_CLK Fall Edge in Clock Gating Mode	16.5		14		ns
t_{HFS3GI}	External FS3 Input Hold Before EPPI_CLK Fall Edge in Clock Gating Mode	1.5		0		ns
Switching Characteristics						
t_{PCLKW}	EPPI_CLK Width[1]	$0.5 \times t_{PCLKPROG} - 2$		$0.5 \times t_{PCLKPROG} - 2$		ns
t_{PCLK}	EPPI_CLK Period[1]	$t_{PCLKPROG} - 2$		$t_{PCLKPROG} - 2$		ns
t_{DFSPI}	Internal FS Delay After EPPI_CLK		2		2	ns
t_{HOFSPI}	Internal FS Hold After EPPI_CLK	–4		–3		ns
t_{DDTPI}	Transmit Data Delay After EPPI_CLK		2		2	ns
t_{HDTPI}	Transmit Data Hold After EPPI_CLK	–4		–3		ns

[1] See Table 18 on Page 52 in Clock Related Operating Conditions for details on the minimum period that may be programmed for $t_{PCLKPROG}$.

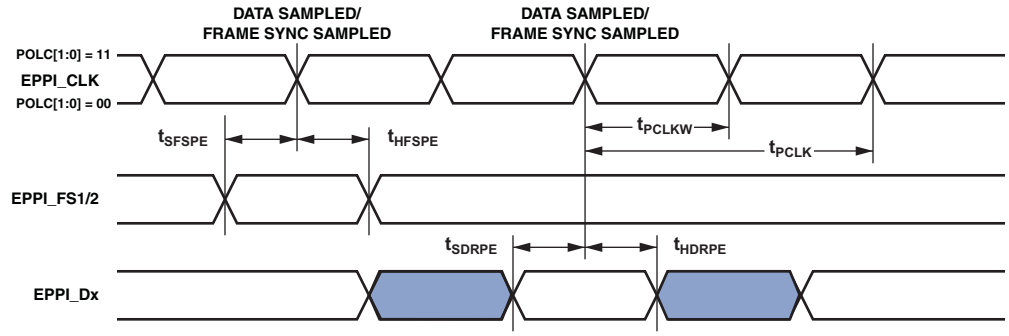


Figure 47. PPI External Clock GP Receive Mode with External Frame Sync Timing

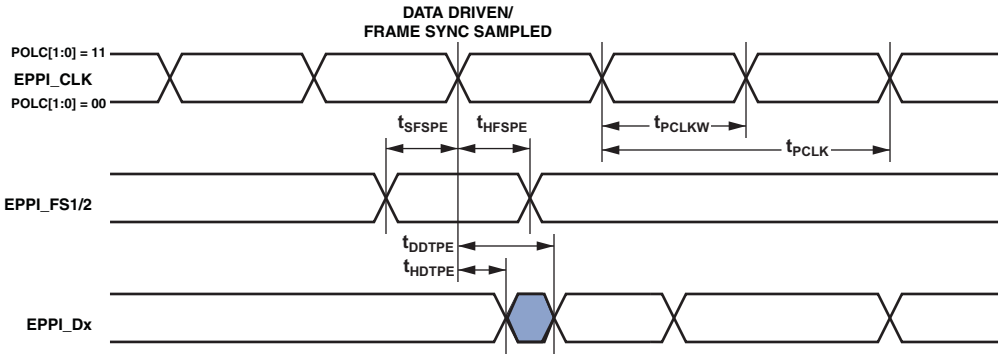
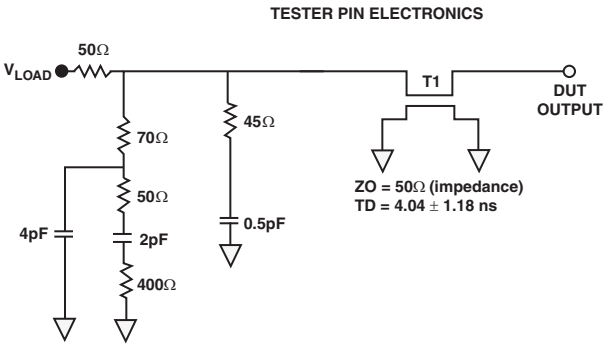


Figure 48. PPI External Clock GP Transmit Mode with External Frame Sync Timing

Capacitive Loading

Output delays and holds are based on standard capacitive loads of an average of 6 pF on all balls (see Figure 64). V_{LOAD} is equal to $V_{DD\_EXT}/2$. The graphs of Figure 65 through Figure 68 show how output rise time varies with capacitance. The delay and hold specifications given should be derated by a factor derived from these figures. The graphs in these figures may not be linear outside the ranges shown.



NOTES:
THE WORST CASE TRANSMISSION LINE DELAY IS SHOWN AND CAN BE USED FOR THE OUTPUT TIMING ANALYSIS TO REFELECT THE TRANSMISSION LINE EFFECT AND MUST BE CONSIDERED. THE TRANSMISSION LINE (TD) IS FOR LOAD ONLY AND DOES NOT AFFECT THE DATA SHEET TIMING SPECIFICATIONS.

ANALOG DEVICES RECOMMENDS USING THE IBIS MODEL TIMING FOR A GIVEN SYSTEM REQUIREMENT. IF NECESSARY, A SYSTEM MAY INCORPORATE EXTERNAL DRIVERS TO COMPENSATE FOR ANY TIMING DIFFERENCES.

Figure 64. Equivalent Device Loading for AC Measurements (Includes All Fixtures)

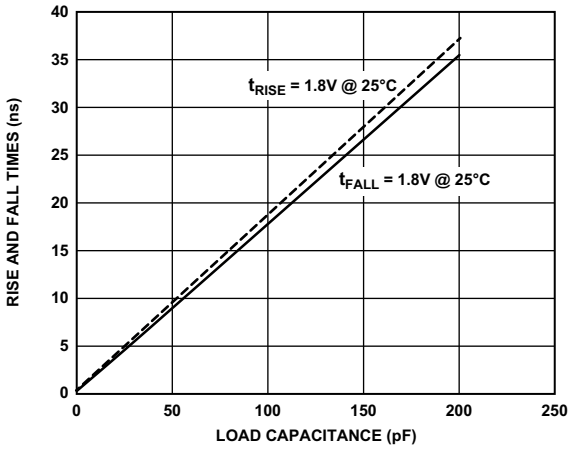


Figure 65. Driver Type A Typical Rise and Fall Times (10% to 90%) vs. Load Capacitance (V_{DD_EXT} = 1.8 V)

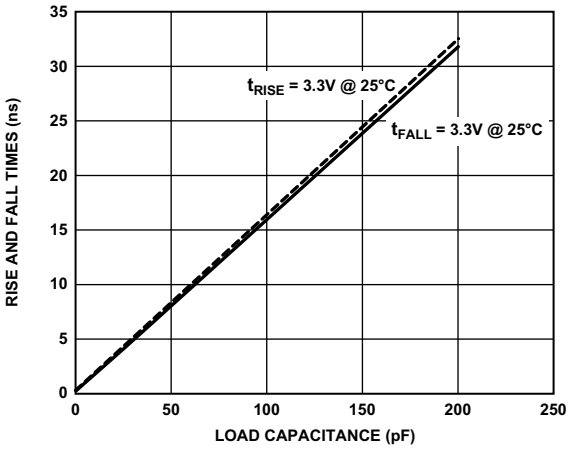


Figure 66. Driver Type A Typical Rise and Fall Times (10% to 90%) vs. Load Capacitance (V_{DD_EXT} = 3.3 V)

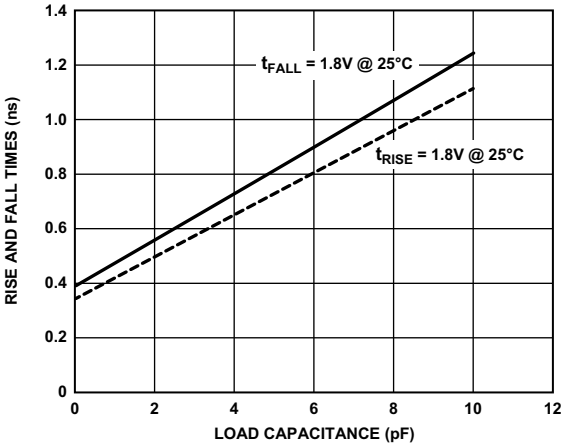


Figure 67. Driver Type B & C Typical Rise and Fall Times (10% to 90%) vs. Load Capacitance (V_{DD_DMC} = 1.8 V)

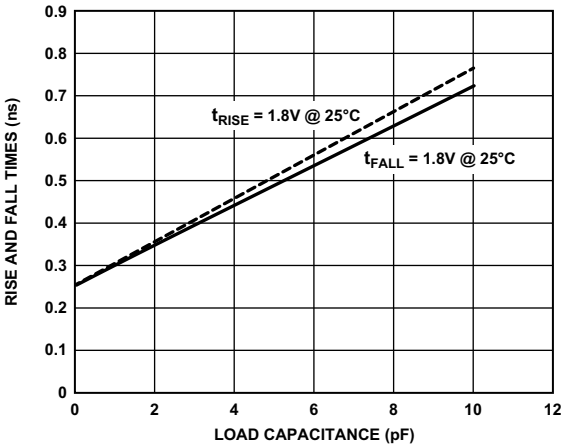


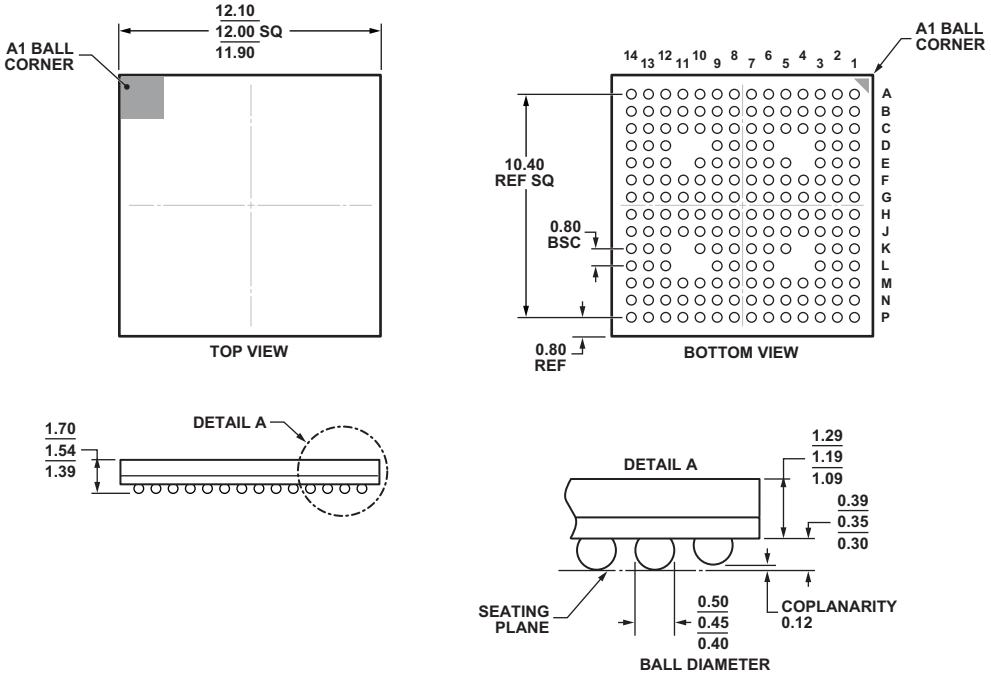
Figure 68. Driver Type B and Driver Type C Typical Rise and Fall Times (10% to 90%) vs. Load Capacitance (V_{DD_DMC} = 1.8 V) for LPDDR

Table 70. ADSP-BF70x 12 mm × 12 mm 88 -Lead LFCSP (QFN) Lead Assignments (Alphabetical by Signal Name)

Signal Name	Lead No.	Signal Name	Lead No.	Signal Name	Lead No.	Signal Name	Lead No.
GND	76	PB_00	52	PC_07	5	USB0_VBUS	34
GND	89	PB_01	48	PC_08	3	USB0_XTAL	31
JTG_TCK_SWCLK	85	PB_02	47	PC_09	2	VDD_EXT	4
JTG_TDI	86	PB_03	46	PC_10	1	VDD_EXT	11
JTG_TDO_SWO	83	PB_04	45	RTC0_CLKIN	21	VDD_EXT	17
JTG_TMS_SWDIO	84	PB_05	44	RTC0_XTAL	20	VDD_EXT	26
$\overline{\text{JTG\_TRST}}$	87	PB_06	43	SYS_BMODE0	66	VDD_EXT	41
PA_00	88	PB_07	42	SYS_BMODE1	67	VDD_EXT	50
PA_01	80	PB_08	40	SYS_CLKIN	57	VDD_EXT	55
PA_02	78	PB_09	39	SYS_CLKOUT	12	VDD_EXT	62
PA_03	75	PB_10	29	SYS_EXTWAKE	79	VDD_EXT	72
PA_04	74	PB_11	28	$\overline{\text{SYS\_FAULT}}$	65	VDD_EXT	82
PA_05	73	PB_12	27	$\overline{\text{SYS\_HWRST}}$	68	VDD_INT	14
PA_06	71	PB_13	25	$\overline{\text{SYS\_NMI}}$	77	VDD_INT	30
PA_07	70	PB_14	24	$\overline{\text{SYS\_RESOUT}}$	15	VDD_INT	51
PA_08	69	PB_15	23	SYS_XTAL	56	VDD_INT	61
PA_09	64	PC_00	16	TWI0_SCL	19	VDD_INT	81
PA_10	63	PC_01	13	TWI0_SDA	18	VDD_OTP	49
PA_11	60	PC_02	10	USB0_CLKIN	32	VDD_RTC	22
PA_12	59	PC_03	9	USB0_DM	37	VDD_USB	36
PA_13	58	PC_04	8	USB0_DP	35		
PA_14	54	PC_05	7	USB0_ID	33		
PA_15	53	PC_06	6	USB0_VBC	38		

OUTLINE DIMENSIONS

Dimensions for the 12 mm × 12 mm CSP_BGA package in Figure 71 are shown in millimeters.



COMPLIANT TO JEDEC STANDARDS MO-275-GGAA-1

Figure 71. 184-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-184-1)
Dimensions shown in millimeters

PLANNED AUTOMOTIVE PRODUCTION PRODUCTS

Model [1, 2, 3]	Max. Core Clock	L2 SRAM	Temperature Grade[4]	Package Description	Package Option
ADBF702WCCPZ3xx	300 MHz	256K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF702WCCPZ4xx	400 MHz	256K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF703WCBCZ3xx	300 MHz	256K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1
ADBF703WCBCZ4xx	400 MHz	256K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1
ADBF704WCCPZ3xx	300 MHz	512K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF704WCCPZ4xx	400 MHz	512K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF705WCBCZ3xx	300 MHz	512K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1
ADBF705WCBCZ4xx	400 MHz	512K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1
ADBF706WCCPZ3xx	300 MHz	1024K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF706WCCPZ4xx	400 MHz	1024K bytes	–40°C to +105°C	88-Lead LFCSP_VQ	CP-88-8
ADBF707WCBCZ3xx	300 MHz	1024K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1
ADBF707WCBCZ4xx	400 MHz	1024K bytes	–40°C to +105°C	184-Ball CSP_BGA	BC-184-1

[1] Select Automotive grade products, supporting –40°C to +105°C $T_{AMBIENT}$ condition, will be available when they appear in the Automotive Products table.
[2] Z = RoHS Compliant Part.
[3] xx denotes the current die revision.
[4] Referenced temperature is ambient temperature. The ambient temperature is not a specification. See Operating Conditions on Page 50 for the junction temperature (T_J) specification which is the only temperature specification.